

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of: Islam et al. Date: January 21, 2010  
Application No.: 10/561,381 Examiner: F.Y. Lopez  
Filing Date: December 16, 2005 Group Art Unit: 2826  
Title: LEAD FRAME ROUTED CHIP PADS FOR SEMICONDUCTOR PACKAGES

**Mail Stop Issue Fee**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT AFTER ALLOWANCE UNDER 37 C.F.R. § 1.312**

Sir:

In response to the Notice of Allowance dated October 29, 2009, the Issue Fee being due on January 29, 2010 but not yet paid, and in accordance with the practice under 37 C.F.R. § 1.312, the Examiner is respectfully requested to amend the above-identified application as follows.

Amendments to the Claims begin on page 2 of this paper.

Remarks begin on page 5 of this paper.

**CERTIFICATE OF MAILING OR TRANSMISSION (37 C.F.R. § 1.8(a))**

I hereby certify that this correspondence (along with any paper referred to as being attached or enclosed) is being:

- deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.
- transmitted by facsimile on the date shown below to the United States Patent and Trademark Office at (571) 273-8300.
- transmitted via the electronic filing system of the United States Patent and Trademark Office on the date shown below and in accordance with 37 C.F.R. § 1.6(a)(4).

January 21, 2010

Signed:

Jay H. Anderson